

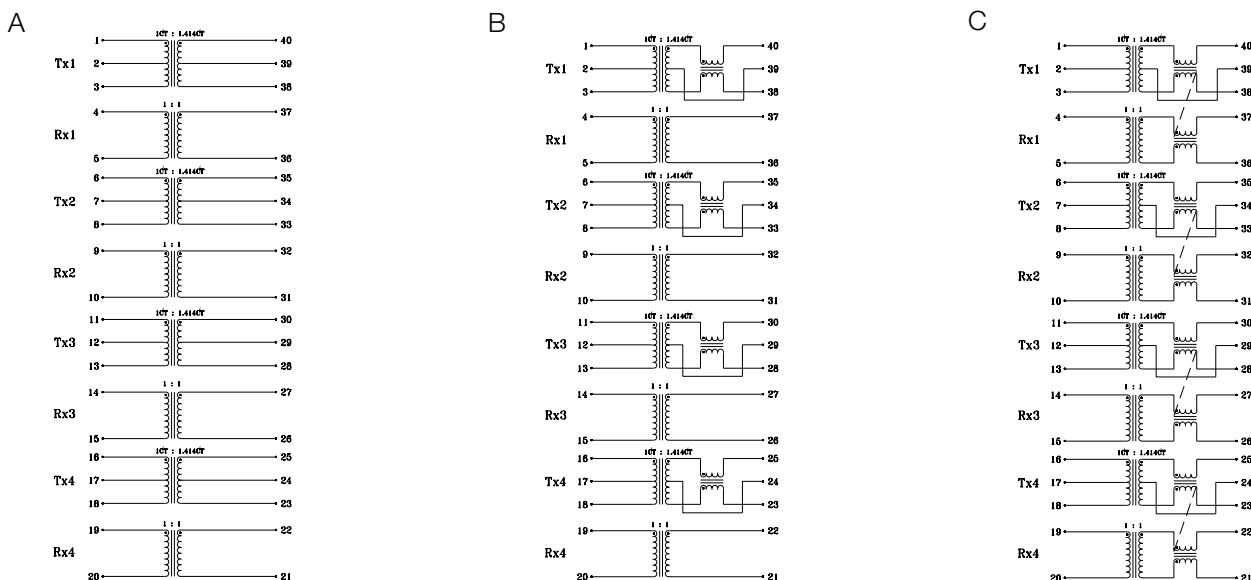
# 10BASE-T NETWORK COMPONENTS

- Designed for use with Level One LXT914/918/944 or Texas Instruments' Quad PHY TNETE 2004 10Base-T transceiver chipsets
- Quad, 4-port design offers optimal space, performance and cost efficiency
- Family of designs offered with common footprint and pinout to accommodate customized EMI requirements
- Low profile surface mount packages, rated to 225°C peak IR reflow temperature
- 2000 Vrms isolation

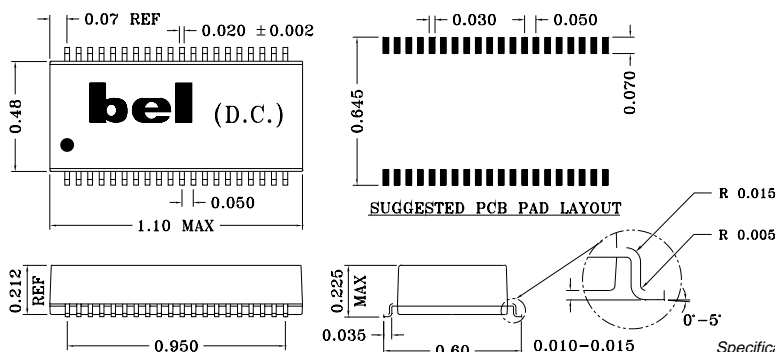
## ELECTRICALS AT 25°C

Part No.	Insertion Loss (dB) Max 1-10MHz	OCL Inductance (μH) Min	Return Loss (dB) Min 1MHz-10MHz	Crosstalk (dB) Min 1MHz-10MHz	CM-CM Rej (dB) Min 10-30MHz 100MHz		Schematic
S553-2940-05	-1.0	100	-18	-40	N/A	N/A	A
S553-2940-06	-1.0	100	-18	-40	-40	-30	B
S553-5999-38	-1.0	100	-18	-40	-40	-30	C

## SCHEMATICS



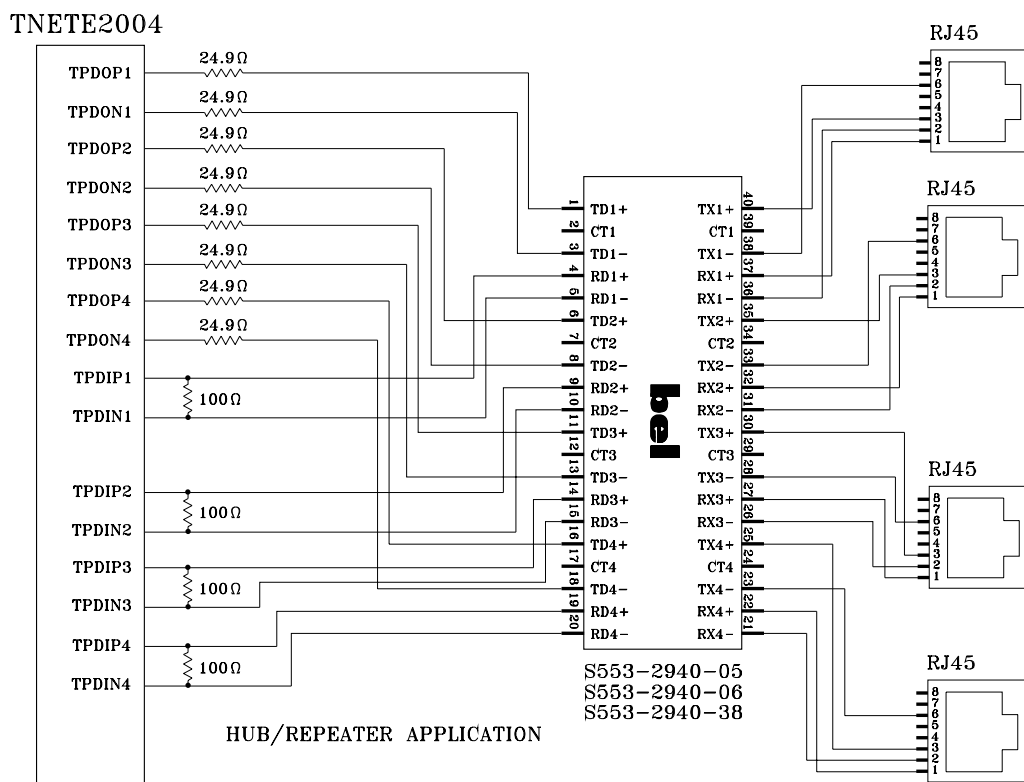
## MECHANICAL



Specifications subject to change without notice.

# 10BASE-T NETWORK COMPONENTS

## APPLICATION CIRCUIT



## APPLICATION NOTES

- Bel has developed a variety of quad, 4-port part types for use with Level One and Texas Instrument quad, 4-port PHY devices that incorporate digital filtering techniques within the silicon itself. Bel's "filterless magnetics" are optimized for this specific application and create a very cost efficient design solution. Each Bel part type contains 4 channels of transmit and receive transformers to provide for wave shaping, high voltage isolation and EMI noise suppression.
- Bel has designed these parts as a family of parts with common footprint and pinouts to enable the designer to customize the use of common mode choke for optimum system performance.
- In multi-port system applications, good PCB layout and proper grounding techniques are very critical to achieve FCC class A and B equipment approvals. Bel recommendations are available and can be provided by contacting our engineering department or your local sales representative.
- Bel's low profile, surface mount packaging is ideal for high speed pick and place machinery. Parts can be shipped on tape and reel for high speed placement. Construction processes have been implemented for thermal compatibility with high temperature IR reflow assembly processing. Post dipping of leads assist with PC board solderability. Each part is optically inspected to meet rigid coplanarity requirements.

### Corporate Office

#### Bel Fuse Inc.

198 Van Vorst Street, Jersey City, NJ 07302-4496  
Tel: 201-432-0463  
Fax: 201-432-9542  
E-Mail: [BelFuse@belfuse.com](mailto:BelFuse@belfuse.com)  
Internet: <http://www.belfuse.com>

### Far East Office

#### Bel Fuse Ltd.

8F/8 Luk Hop Street  
San Po Kong  
Kowloon, Hong Kong  
Tel: 852-2328-5515  
Fax: 852-2352-3706

### European Office

#### Bel Fuse Europe Ltd.

Preston Technology Management Centre  
Marsh Lane, Preston PR1 8UD  
Lancashire, U.K.  
Tel: 44-1772-556601  
Fax: 44-1772-888366